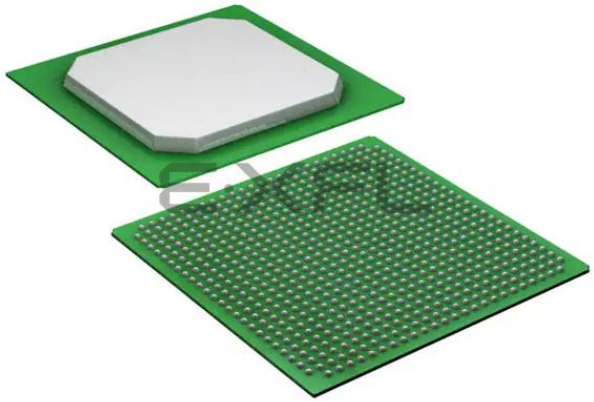

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Details	
Product Status	Active
Number of LABs/CLBs	9360
Number of Logic Elements/Cells	149760
Total RAM Bits	6635520
Number of I/O	393
Number of Gates	-
Voltage - Supply	1.16V ~ 1.24V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	672-BGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4cgx150df27i7n

DC Characteristics

This section lists the I/O leakage current, pin capacitance, on-chip termination (OCT) tolerance, and bus hold specifications for Cyclone IV devices.

Supply Current

The device supply current requirement is the minimum current drawn from the power supply pins that can be used as a reference for power size planning. Use the Excel-based early power estimator (EPE) to get the supply current estimates for your design because these currents vary greatly with the resources used. Table 1–6 lists the I/O pin leakage current for Cyclone IV devices.

Table 1–6. I/O Pin Leakage Current for Cyclone IV Devices *(1), (2)*

Symbol	Parameter	Conditions	Device	Min	Typ	Max	Unit
I_I	Input pin leakage current	V_I = 0 V to $V_{CCIOMAX}$	—	–10	—	10	µA
I_{OZ}	Tristated I/O pin leakage current	V_O = 0 V to $V_{CCIOMAX}$	—	–10	—	10	µA

Notes to Table 1–6:

(1) This value is specified for normal device operation. The value varies during device power-up. This applies for all V_{CCIO} settings (3.3, 3.0, 2.5, 1.8, 1.5, and 1.2 V).

(2) The 10 µA I/O leakage current limit is applicable when the internal clamping diode is off. A higher current can be observed when the diode is on.

Bus Hold

The bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1–7 lists bus hold specifications for Cyclone IV devices.

Table 1–7. Bus Hold Parameter for Cyclone IV Devices (Part 1 of 2) *(1)*

Parameter	Condition	V_{CCIO} (V)												Unit
		1.2		1.5		1.8		2.5		3.0		3.3		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus hold low, sustaining current	$V_{IN} > V_{IL}$ (maximum)	8	—	12	—	30	—	50	—	70	—	70	—	µA
Bus hold high, sustaining current	$V_{IN} < V_{IL}$ (minimum)	–8	—	–12	—	–30	—	–50	—	–70	—	–70	—	µA
Bus hold low, overdrive current	0 V < V_{IN} < V_{CCIO}	—	125	—	175	—	200	—	300	—	500	—	500	µA
Bus hold high, overdrive current	0 V < V_{IN} < V_{CCIO}	—	–125	—	–175	—	–200	—	–300	—	–500	—	–500	µA

Example 1–1 shows how to calculate the change of 50-Ω I/O impedance from 25°C at 3.0 V to 85°C at 3.15 V.

Example 1–1. Impedance Change

$\Delta R_V = (3.15 – 3) \times 1000 \times –0.026 = –3.83$

$\Delta R_T = (85 – 25) \times 0.262 = 15.72$

Because ΔR_V is negative,

$MF_V = 1 / (3.83/100 + 1) = 0.963$

Because ΔR_T is positive,

$MF_T = 15.72/100 + 1 = 1.157$

$MF = 0.963 \times 1.157 = 1.114$

$R_{final} = 50 \times 1.114 = 55.71\ \Omega$

Pin Capacitance

Table 1–11 lists the pin capacitance for Cyclone IV devices.

Table 1–11. Pin Capacitance for Cyclone IV Devices *(1)*

Symbol	Parameter	Typical – Quad Flat Pack (QFP)	Typical – Quad Flat No Leads (QFN)	Typical – Ball-Grid Array (BGA)	Unit
C_{IOTB}	Input capacitance on top and bottom I/O pins	7	7	6	pF
C_{IOLR}	Input capacitance on right I/O pins	7	7	5	pF
C_{LVDSLR}	Input capacitance on right I/O pins with dedicated LVDS output	8	8	7	pF
C_{VREFLR} *(2)*	Input capacitance on right dual-purpose VREF pin when used as V_{REF} or user I/O pin	21	21	21	pF
C_{VREFTB} *(2)*	Input capacitance on top and bottom dual-purpose VREF pin when used as V_{REF} or user I/O pin	23 *(3)*	23	23	pF
C_{CLKTB}	Input capacitance on top and bottom dedicated clock input pins	7	7	6	pF
C_{CLKLR}	Input capacitance on right dedicated clock input pins	6	6	5	pF

Notes to Table 1–11:

(1) The pin capacitance applies to FBGA, UBGA, and MBGA packages.

(2) When you use the VREF pin as a regular input or output, you can expect a reduced performance of toggle rate and t_{CO} because of higher pin capacitance.

(3) C_{VREFTB} for the EP4CE22 device is 30 pF.

Internal Weak Pull-Up and Weak Pull-Down Resistor

Table 1–12 lists the weak pull-up and pull-down resistor values for Cyclone IV devices.

Table 1–12. Internal Weak Pull-Up and Weak Pull-Down Resistor Values for Cyclone IV Devices *(1)*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{\_PU}$	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option	V_{CCIO} = 3.3 V ± 5% *(2), (3)*	7	25	41	kΩ
		V_{CCIO} = 3.0 V ± 5% *(2), (3)*	7	28	47	kΩ
		V_{CCIO} = 2.5 V ± 5% *(2), (3)*	8	35	61	kΩ
		V_{CCIO} = 1.8 V ± 5% *(2), (3)*	10	57	108	kΩ
		V_{CCIO} = 1.5 V ± 5% *(2), (3)*	13	82	163	kΩ
		V_{CCIO} = 1.2 V ± 5% *(2), (3)*	19	143	351	kΩ
$R_{\_PD}$	Value of the I/O pin pull-down resistor before and during configuration	V_{CCIO} = 3.3 V ± 5% *(4)*	6	19	30	kΩ
		V_{CCIO} = 3.0 V ± 5% *(4)*	6	22	36	kΩ
		V_{CCIO} = 2.5 V ± 5% *(4)*	6	25	43	kΩ
		V_{CCIO} = 1.8 V ± 5% *(4)*	7	35	71	kΩ
		V_{CCIO} = 1.5 V ± 5% *(4)*	8	50	112	kΩ

Notes to Table 1–12:

(1) All I/O pins have an option to enable weak pull-up except the configuration, test, and JTAG pins. The weak pull-down feature is only available for JTAG TCK.

(2) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

(3) $R_{\_PU} = (V_{CCIO} – V_I)/I_{R\_PU}$
Minimum condition: –40°C; $V_{CCIO} = V_{CC}$ + 5%, $V_I = V_{CC}$ + 5% – 50 mV;
Typical condition: 25°C; $V_{CCIO} = V_{CC}$, V_I = 0 V;
Maximum condition: 100°C; $V_{CCIO} = V_{CC}$ – 5%, V_I = 0 V; in which V_I refers to the input voltage at the I/O pin.

(4) $R_{\_PD} = V_I/I_{R\_PD}$
Minimum condition: –40°C; $V_{CCIO} = V_{CC}$ + 5%, V_I = 50 mV;
Typical condition: 25°C; $V_{CCIO} = V_{CC}$, $V_I = V_{CC}$ – 5%;
Maximum condition: 100°C; $V_{CCIO} = V_{CC}$ – 5%, $V_I = V_{CC}$ – 5%; in which V_I refers to the input voltage at the I/O pin.

Hot-Socketing

Table 1–13 lists the hot-socketing specifications for Cyclone IV devices.

Table 1–13. Hot-Socketing Specifications for Cyclone IV Devices

Symbol	Parameter	Maximum
$I_{IOPIN(DC)}$	DC current per I/O pin	300 µA
$I_{IOPIN(AC)}$	AC current per I/O pin	8 mA *(1)*
$I_{XCVRTX(DC)}$	DC current per transceiver TX pin	100 mA
$I_{XCVRRX(DC)}$	DC current per transceiver RX pin	50 mA

Note to Table 1–13:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |IIOPIN| = C dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.

☞ During hot-socketing, the I/O pin capacitance is less than 15 pF and the clock pin capacitance is less than 20 pF.

Schmitt Trigger Input

Cyclone IV devices support Schmitt trigger input on the TDI, TMS, TCK, nSTATUS, nCONFIG, nCE, CONF_DONE, and DCLK pins. A Schmitt trigger feature introduces hysteresis to the input signal for improved noise immunity, especially for signals with slow edge rate. Table 1–14 lists the hysteresis specifications across the supported V_{CCIO} range for Schmitt trigger inputs in Cyclone IV devices.

Table 1–14. Hysteresis Specifications for Schmitt Trigger Input in Cyclone IV Devices

Symbol	Parameter	Conditions (V)	Minimum	Unit
$V_{SCHMITT}$	Hysteresis for Schmitt trigger input	V_{CCIO} = 3.3	200	mV
		V_{CCIO} = 2.5	200	mV
		V_{CCIO} = 1.8	140	mV
		V_{CCIO} = 1.5	110	mV

I/O Standard Specifications

The following tables list input voltage sensitivities (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}), for various I/O standards supported by Cyclone IV devices. Table 1–15 through Table 1–20 provide the I/O standard specifications for Cyclone IV devices.

Table 1–15. Single-Ended I/O Standard Specifications for Cyclone IV Devices (1), (2)

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA) (4)	I_{OH} (mA) (4)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
3.3-V LVTTL (3)	3.135	3.3	3.465	—	0.8	1.7	3.6	0.45	2.4	4	–4
3.3-V LVCMOS (3)	3.135	3.3	3.465	—	0.8	1.7	3.6	0.2	V_{CCIO} – 0.2	2	–2
3.0-V LVTTL (3)	2.85	3.0	3.15	–0.3	0.8	1.7	V_{CCIO} + 0.3	0.45	2.4	4	–4
3.0-V LVCMOS (3)	2.85	3.0	3.15	–0.3	0.8	1.7	V_{CCIO} + 0.3	0.2	V_{CCIO} – 0.2	0.1	–0.1
2.5 V (3)	2.375	2.5	2.625	–0.3	0.7	1.7	V_{CCIO} + 0.3	0.4	2.0	1	–1
1.8 V	1.71	1.8	1.89	–0.3	0.35 x V_{CCIO}	0.65 x V_{CCIO}	2.25	0.45	V_{CCIO} – 0.45	2	–2
1.5 V	1.425	1.5	1.575	–0.3	0.35 x V_{CCIO}	0.65 x V_{CCIO}	V_{CCIO} + 0.3	0.25 x V_{CCIO}	0.75 x V_{CCIO}	2	–2
1.2 V	1.14	1.2	1.26	–0.3	0.35 x V_{CCIO}	0.65 x V_{CCIO}	V_{CCIO} + 0.3	0.25 x V_{CCIO}	0.75 x V_{CCIO}	2	–2
3.0-V PCI	2.85	3.0	3.15	—	0.3 x V_{CCIO}	0.5 x V_{CCIO}	V_{CCIO} + 0.3	0.1 x V_{CCIO}	0.9 x V_{CCIO}	1.5	–0.5
3.0-V PCI-X	2.85	3.0	3.15	—	0.35 x V_{CCIO}	0.5 x V_{CCIO}	V_{CCIO} + 0.3	0.1 x V_{CCIO}	0.9 x V_{CCIO}	1.5	–0.5

Notes to Table 1–15:

(1) For voltage-referenced receiver input waveform and explanation of terms used in Table 1–15, refer to "Glossary" on page 1–37.

(2) AC load CL = 10 pF

(3) For more information about interfacing Cyclone IV devices with 3.3/3.0/2.5-V LVTTL/LVCMOS I/O standards, refer to *AN 447: Interfacing Cyclone III and Cyclone IV Devices with 3.3/3.0/2.5-V LVTTL/LVCMOS I/O Systems*.

(4) To meet the I_{OL} and I_{OH} specifications, you must set the current strength settings accordingly. For example, to meet the **3.3-V LVTTL** specification (4 mA), set the current strength settings to 4 mA or higher. Setting at lower current strength may not meet the I_{OL} and I_{OH} specifications in the handbook.

Table 1–16. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Cyclone IV Devices *(1)*

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V) *(2)*		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	1.19	1.25	1.31	V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04
SSTL-18 Class I, II	1.7	1.8	1.9	0.833	0.9	0.969	V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	0.85	0.9	0.95
HSTL-15 Class I, II	1.425	1.5	1.575	0.71	0.75	0.79	0.71	0.75	0.79
HSTL-12 Class I, II	1.14	1.2	1.26	0.48 x V_{CCIO} *(3)*	0.5 x V_{CCIO} *(3)*	0.52 x V_{CCIO} *(3)*	—	0.5 x V_{CCIO}	—
				0.47 x V_{CCIO} *(4)*	0.5 x V_{CCIO} *(4)*	0.53 x V_{CCIO} *(4)*			

Notes to Table 1–16:

(1) For an explanation of terms used in Table 1–16, refer to "Glossary" on page 1–37.
(2) V_{TT} of the transmitting device must track V_{REF} of the receiving device.
(3) Value shown refers to DC input reference voltage, $V_{REF(DC)}$.
(4) Value shown refers to AC input reference voltage, $V_{REF(AC)}$.

Table 1–17. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Cyclone IV Devices

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)		$V_{IH(AC)}$ (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Max	Min	Max	Min	Max	Min	Max	Max	Min		
SSTL-2 Class I	—	V_{REF} – 0.18	V_{REF} + 0.18	—	—	V_{REF} – 0.35	V_{REF} + 0.35	—	V_{TT} – 0.57	V_{TT} + 0.57	8.1	–8.1
SSTL-2 Class II	—	V_{REF} – 0.18	V_{REF} + 0.18	—	—	V_{REF} – 0.35	V_{REF} + 0.35	—	V_{TT} – 0.76	V_{TT} + 0.76	16.4	–16.4
SSTL-18 Class I	—	V_{REF} – 0.125	V_{REF} + 0.125	—	—	V_{REF} – 0.25	V_{REF} + 0.25	—	V_{TT} – 0.475	V_{TT} + 0.475	6.7	–6.7
SSTL-18 Class II	—	V_{REF} – 0.125	V_{REF} + 0.125	—	—	V_{REF} – 0.25	V_{REF} + 0.25	—	0.28	V_{CCIO} – 0.28	13.4	–13.4
HSTL-18 Class I	—	V_{REF} – 0.1	V_{REF} + 0.1	—	—	V_{REF} – 0.2	V_{REF} + 0.2	—	0.4	V_{CCIO} – 0.4	8	–8
HSTL-18 Class II	—	V_{REF} – 0.1	V_{REF} + 0.1	—	—	V_{REF} – 0.2	V_{REF} + 0.2	—	0.4	V_{CCIO} – 0.4	16	–16
HSTL-15 Class I	—	V_{REF} – 0.1	V_{REF} + 0.1	—	—	V_{REF} – 0.2	V_{REF} + 0.2	—	0.4	V_{CCIO} – 0.4	8	–8
HSTL-15 Class II	—	V_{REF} – 0.1	V_{REF} + 0.1	—	—	V_{REF} – 0.2	V_{REF} + 0.2	—	0.4	V_{CCIO} – 0.4	16	–16
HSTL-12 Class I	–0.15	V_{REF} – 0.08	V_{REF} + 0.08	V_{CCIO} + 0.15	–0.24	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.24	0.25 × V_{CCIO}	0.75 × V_{CCIO}	8	–8
HSTL-12 Class II	–0.15	V_{REF} – 0.08	V_{REF} + 0.08	V_{CCIO} + 0.15	–0.24	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.24	0.25 × V_{CCIO}	0.75 × V_{CCIO}	14	–14

For more information about receiver input and transmitter output waveforms, and for other differential I/O standards, refer to the *I/O Features in Cyclone IV Devices* chapter.

Table 1–18. Differential SSTL I/O Standard Specifications for Cyclone IV Devices *(1)*

I/O Standard	V_{CCIO} (V)			$V_{Swing(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{Swing(AC)}$ (V)		$V_{OX(AC)}$ (V)		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.36	V_{CCIO}	$V_{CCIO}/2 - 0.2$	—	$V_{CCIO}/2 + 0.2$	0.7	V_{CCIO}	$V_{CCIO}/2 - 0.125$	—	$V_{CCIO}/2 + 0.125$
SSTL-18 Class I, II	1.7	1.8	1.90	0.25	V_{CCIO}	$V_{CCIO}/2 - 0.175$	—	$V_{CCIO}/2 + 0.175$	0.5	V_{CCIO}	$V_{CCIO}/2 - 0.125$	—	$V_{CCIO}/2 + 0.125$

Note to Table 1–18:

(1) Differential SSTL requires a V_{REF} input.

Table 1–19. Differential HSTL I/O Standard Specifications for Cyclone IV Devices *(1)*

I/O Standard	V_{CCIO} (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.85	—	0.95	0.85	—	0.95	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.71	—	0.79	0.71	—	0.79	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V_{CCIO}	$0.48 \times V_{CCIO}$	—	$0.52 \times V_{CCIO}$	$0.48 \times V_{CCIO}$	—	$0.52 \times V_{CCIO}$	0.3	$0.48 \times V_{CCIO}$

Note to Table 1–19:

(1) Differential HSTL requires a V_{REF} input.

Table 1–20. Differential I/O Standard Specifications for Cyclone IV Devices *(1)* **(Part 1 of 2)**

I/O Standard	V_{CCIO} (V)			V_{ID} (mV)		V_{ICM} (V) *(2)*			V_{OD} (mV) *(3)*			V_{OS} (V) *(3)*		
	Min	Typ	Max	Min	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
LVPECL (Row I/Os) *(6)*	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq 500$ Mbps	1.80	—	—	—	—	—	—
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	$D_{MAX} >$ 700 Mbps	1.55						
LVPECL (Column I/Os) *(6)*	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq$ 500 Mbps	1.80	—	—	—	—	—	—
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	$D_{MAX} >$ 700 Mbps	1.55						
LVDS (Row I/Os)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq$ 500 Mbps	1.80	247	—	600	1.125	1.25	1.375
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	$D_{MAX} >$ 700 Mbps	1.55						

Table 1–20. Differential I/O Standard Specifications for Cyclone IV Devices (1) (Part 2 of 2)

I/O Standard	V_{CCIO} (V)			V_{ID} (mV)		V_{ICM} (V) (2)			V_{OD} (mV) (3)			V_{OS} (V) (3)		
	Min	Typ	Max	Min	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
LVDS (Column I/Os)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq$ 500 Mbps	1.80	247	—	600	1.125	1.25	1.375
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	D_{MAX} > 700 Mbps	1.55						
BLVDS (Row I/Os) (4)	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—
BLVDS (Column I/Os) (4)	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—
mini-LVDS (Row I/Os) (5)	2.375	2.5	2.625	—	—	—	—	—	300	—	600	1.0	1.2	1.4
mini-LVDS (Column I/Os) (5)	2.375	2.5	2.625	—	—	—	—	—	300	—	600	1.0	1.2	1.4
RSDS® (Row I/Os) (5)	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.5
RSDS (Column I/Os) (5)	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.5
PPDS (Row I/Os) (5)	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.4
PPDS (Column I/Os) (5)	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.4

Notes to Table 1–20:

(1) For an explanation of terms used in Table 1–20, refer to "Glossary" on page 1–37.

(2) V_{IN} range: 0 V $\leq V_{IN} \leq$ 1.85 V.

(3) R_L range: 90 $\leq R_L \leq$ 110 Ω.

(4) There are no fixed V_{IN}, V_{OD}, and V_{OS} specifications for BLVDS. They depend on the system topology.

(5) The Mini-LVDS, RSDS, and PPDS standards are only supported at the output pins.

(6) The LVPECL I/O standard is only supported on dedicated clock input pins. This I/O standard is not supported for output pins.

Power Consumption

Use the following methods to estimate power for a design:

- the Excel-based EPE
- the Quartus® II PowerPlay power analyzer feature

The interactive Excel-based EPE is used prior to designing the device to get a magnitude estimate of the device power. The Quartus II PowerPlay power analyzer provides better quality estimates based on the specifics of the design after place-and-route is complete. The PowerPlay power analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, combined with detailed circuit models, can yield very accurate power estimates.

For more information about power estimation tools, refer to the *Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in volume 3 of the *Quartus II Handbook*.

Switching Characteristics

This section provides performance characteristics of Cyclone IV core and periphery blocks for commercial grade devices.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The upper-right hand corner of these tables show the designation as “Preliminary”.
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

Transceiver Performance Specifications

Table 1–21 lists the Cyclone IV GX transceiver specifications.

Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 1 of 4)

Symbol/ Description	Conditions	C6			C7, I7			C8			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reference Clock											
Supported I/O Standards	1.2 V PCML, 1.5 V PCML, 3.3 V PCML, Differential LVPECL, LVDS, HCSL										
Input frequency from REFCLK input pins	—	50	—	156.25	50	—	156.25	50	—	156.25	MHz
Spread-spectrum modulating clock frequency	Physical interface for PCI Express (PIPE) mode	30	—	33	30	—	33	30	—	33	kHz
Spread-spectrum downspread	PIPE mode	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—
Peak-to-peak differential input voltage	—	0.1	—	1.6	0.1	—	1.6	0.1	—	1.6	V
V_{ICM} (AC coupled)	—	1100 ± 5%			1100 ± 5%			1100 ± 5%			mV
V_{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise *(1)*	Frequency offset = 1 MHz – 8 MHZ	—	—	–123	—	—	–123	—	—	–123	dBc/Hz
Transmitter REFCLK Total Jitter *(1)*		—	—	42.3	—	—	42.3	—	—	42.3	ps
R_{ref}	—	—	2000 ± 1%	—	—	2000 ± 1%	—	—	2000 ± 1%	—	Ω
Transceiver Clock											
cal_blk_clk clock frequency	—	10	—	125	10	—	125	10	—	125	MHz
fixedclk clock frequency	PCIe Receiver Detect	—	125	—	—	125	—	—	125	—	MHz
reconfig_clk clock frequency	Dynamic reconfiguration clock frequency	2.5/ 37.5 *(2)*	—	50	2.5/ 37.5 *(2)*	—	50	2.5/ 37.5 *(2)*	—	50	MHz
Delta time between reconfig_clk	—	—	—	2	—	—	2	—	—	2	ms
Transceiver block minimum power-down pulse width	—	—	1	—	—	1	—	—	1	—	µs

Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 2 of 4)

Symbol/ Description	Conditions	C6			C7, I7			C8			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Receiver											
Supported I/O Standards	1.4 V PCML, 1.5 V PCML, 2.5 V PCML, LVPECL, LVDS										
Data rate (F324 and smaller package) *(15)*	—	600	—	2500	600	—	2500	600	—	2500	Mbps
Data rate (F484 and larger package) *(15)*	—	600	—	3125	600	—	3125	600	—	2500	Mbps
Absolute V_{MAX} for a receiver pin *(3)*	—	—	—	1.6	—	—	1.6	—	—	1.6	V
Operational V_{MAX} for a receiver pin	—	—	—	1.5	—	—	1.5	—	—	1.5	V
Absolute V_{MIN} for a receiver pin	—	–0.4	—	—	–0.4	—	—	–0.4	—	—	V
Peak-to-peak differential input voltage V_{ID} (diff p-p)	V_{ICM} = 0.82 V setting, Data Rate = 600 Mbps to 3.125 Gbps	0.1	—	2.7	0.1	—	2.7	0.1	—	2.7	V
V_{ICM}	V_{ICM} = 0.82 V setting	—	820 ± 10%	—	—	820 ± 10%	—	—	820 ± 10%	—	mV
Differential on-chip termination resistors	100–Ω setting	—	100	—	—	100	—	—	100	—	Ω
	150–Ω setting	—	150	—	—	150	—	—	150	—	Ω
Differential and common mode return loss	PIPE, Serial Rapid I/O SR, SATA, CPRI LV, SDI, XAUI	Compliant									—
Programmable ppm detector *(4)*	—	± 62.5, 100, 125, 200, 250, 300									ppm
Clock data recovery (CDR) ppm tolerance (without spread-spectrum clocking enabled)	—	—	—	±300 *(5)*, ±350 *(6)*, *(7)*	—	—	±300 *(5)*, ±350 *(6)*, *(7)*	—	—	±300 *(5)*, ±350 *(6)*, *(7)*	ppm
CDR ppm tolerance (with synchronous spread-spectrum clocking enabled) *(8)*	—	—	—	350 to –5350 *(7)*, *(9)*	—	—	350 to –5350 *(7)*, *(9)*	—	—	350 to –5350 *(7)*, *(9)*	ppm
Run length	—	—	80	—	—	80	—	—	80	—	UI
Programmable equalization	No Equalization	—	—	1.5	—	—	1.5	—	—	1.5	dB
	Medium Low	—	—	4.5	—	—	4.5	—	—	4.5	dB
	Medium High	—	—	5.5	—	—	5.5	—	—	5.5	dB
	High	—	—	7	—	—	7	—	—	7	dB

Figure 1–2 shows the lock time parameters in manual mode.

LTD = lock-to-data. LTR = lock-to-reference.

Figure 1–2. Lock Time Parameters for Manual Mode

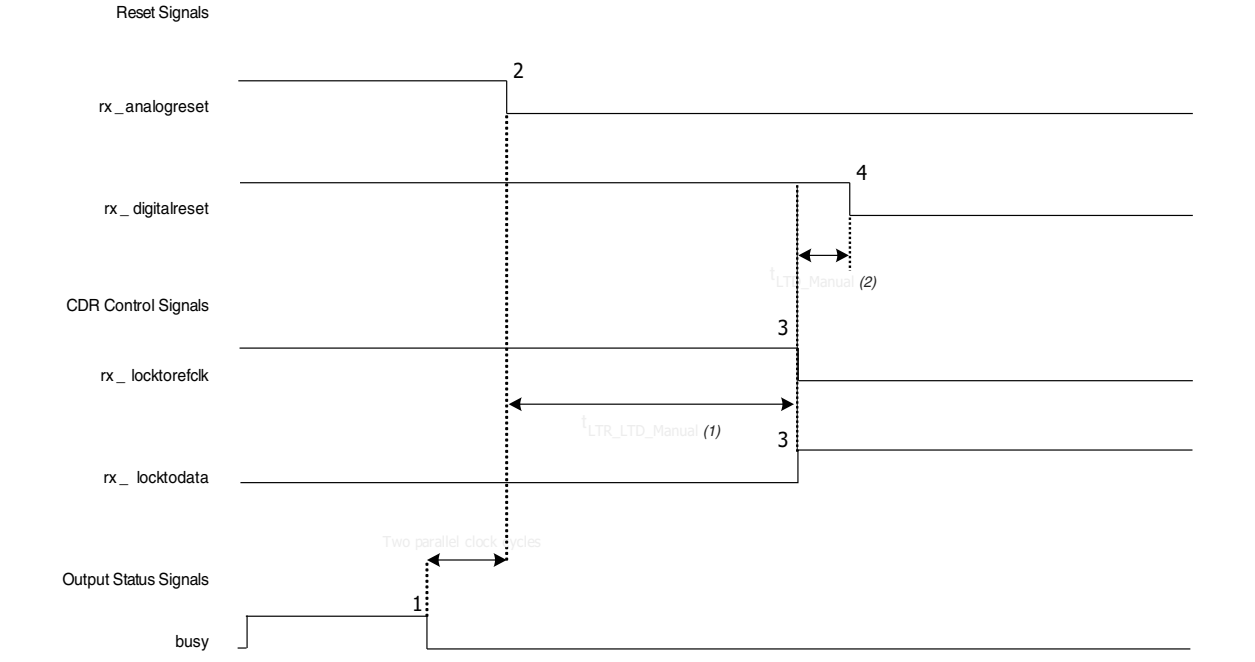


Figure 1–3 shows the lock time parameters in automatic mode.

Figure 1–3. Lock Time Parameters for Automatic Mode

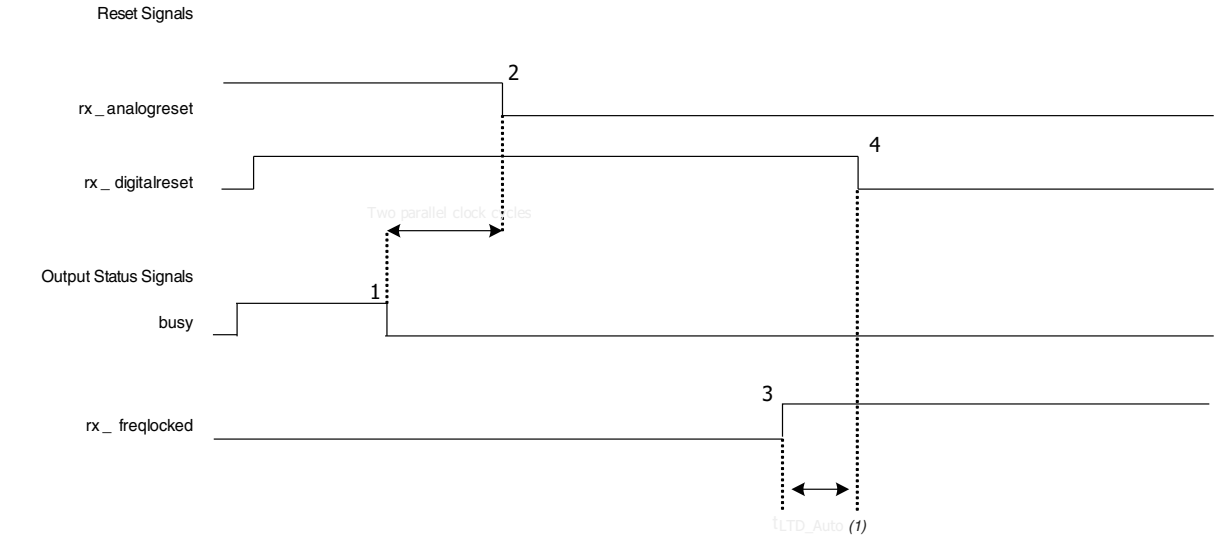


Table 1–23 lists the Cyclone IV GX transceiver block AC specifications.

Table 1–23. Transceiver Block AC Specification for Cyclone IV GX Devices *(1), (2)*

Symbol/ Description	Conditions	C6			C7, I7			C8			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
PCIe Transmit Jitter Generation *(3)*											
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	—	—	0.25	—	—	0.25	—	—	0.25	UI
PCIe Receiver Jitter Tolerance *(3)*											
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	> 0.6			> 0.6			> 0.6			UI
GIGE Transmit Jitter Generation *(4)*											
Deterministic jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.14	—	—	0.14	—	—	0.14	UI
Total jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.279	—	—	0.279	—	—	0.279	UI
GIGE Receiver Jitter Tolerance *(4)*											
Deterministic jitter tolerance (peak-to-peak)	Pattern = CJPAT	> 0.4			> 0.4			> 0.4			UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Pattern = CJPAT	> 0.66			> 0.66			> 0.66			UI

Notes to Table 1–23:

(1) Dedicated `refclk` pins were used to drive the input reference clocks.
(2) The jitter numbers specified are valid for the stated conditions only.
(3) The jitter numbers for PIPE are compliant to the PCIe Base Specification 2.0.
(4) The jitter numbers for GIGE are compliant to the IEEE802.3-2002 Specification.

Core Performance Specifications

The following sections describe the clock tree specifications, PLLs, embedded multiplier, memory block, and configuration specifications for Cyclone IV Devices.

Clock Tree Specifications

Table 1–24 lists the clock tree specifications for Cyclone IV devices.

Table 1–24. Clock Tree Performance for Cyclone IV Devices ***(Part 1 of 2)***

Device	Performance								Unit
	C6	C7	C8	C8L *(1)*	C9L *(1)*	I7	I8L *(1)*	A7	
EP4CE6	500	437.5	402	362	265	437.5	362	402	MHz
EP4CE10	500	437.5	402	362	265	437.5	362	402	MHz
EP4CE15	500	437.5	402	362	265	437.5	362	402	MHz
EP4CE22	500	437.5	402	362	265	437.5	362	402	MHz
EP4CE30	500	437.5	402	362	265	437.5	362	402	MHz
EP4CE40	500	437.5	402	362	265	437.5	362	402	MHz

Table 1–25. PLL Specifications for Cyclone IV Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
t_{DLOCK}	Time required to lock dynamically (after switchover, reconfiguring any non-post-scale counters/delays or areset is deasserted)	—	—	1	ms
$t_{OUTJITTER\_PERIOD\_DEDCLK}$ (6)	Dedicated clock output period jitter $F_{OUT} \geq 100$ MHz	—	—	300	ps
	$F_{OUT} < 100$ MHz	—	—	30	mUI
$t_{OUTJITTER\_CCJ\_DEDCLK}$ (6)	Dedicated clock output cycle-to-cycle jitter $F_{OUT} \geq 100$ MHz	—	—	300	ps
	$F_{OUT} < 100$ MHz	—	—	30	mUI
$t_{OUTJITTER\_PERIOD\_IO}$ (6)	Regular I/O period jitter $F_{OUT} \geq 100$ MHz	—	—	650	ps
	$F_{OUT} < 100$ MHz	—	—	75	mUI
$t_{OUTJITTER\_CCJ\_IO}$ (6)	Regular I/O cycle-to-cycle jitter $F_{OUT} \geq 100$ MHz	—	—	650	ps
	$F_{OUT} < 100$ MHz	—	—	75	mUI
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on areset signal.	10	—	—	ns
$t_{CONFIGPLL}$	Time required to reconfigure scan chains for PLLs	—	3.5 (7)	—	SCANCLK cycles
$f_{SCANCLK}$	scanclk frequency	—	—	100	MHz
$t_{CASC\_OUTJITTER\_PERIOD\_DEDCLK}$ (8), (9)	Period jitter for dedicated clock output in cascaded PLLs ($F_{OUT} \geq 100$ MHz)	—	—	425	ps
	Period jitter for dedicated clock output in cascaded PLLs ($F_{OUT} < 100$ MHz)	—	—	42.5	mUI

Notes to Table 1–25:

(1) This table is applicable for general purpose PLLs and multipurpose PLLs.

(2) You must connect V_{CCD_PLL} to V_{CCINT} through the decoupling capacitor and ferrite bead.

(3) This parameter is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(4) The V_{CO} frequency reported by the Quartus II software in the PLL Summary section of the compilation report takes into consideration the V_{CO} post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.

(5) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source that is less than 200 ps.

(6) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.99999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL when an input jitter of 30 ps is applied.

(7) With 100-MHz scanclk frequency.

(8) The cascaded PLLs specification is applicable only with the following conditions:

- Upstream PLL—0.59 MHz ≤ Upstream PLL bandwidth < 1 MHz
- Downstream PLL—Downstream PLL bandwidth > 2 MHz

(9) PLL cascading is not supported for transceiver applications.

Embedded Multiplier Specifications

Table 1–26 lists the embedded multiplier specifications for Cyclone IV devices.

Table 1–26. Embedded Multiplier Specifications for Cyclone IV Devices

Mode	Resources Used	Performance					Unit
	Number of Multipliers	C6	C7, I7, A7	C8	C8L, I8L	C9L	
9 × 9-bit multiplier	1	340	300	260	240	175	MHz
18 × 18-bit multiplier	1	287	250	200	185	135	MHz

Memory Block Specifications

Table 1–27 lists the M9K memory block specifications for Cyclone IV devices.

Table 1–27. Memory Block Performance Specifications for Cyclone IV Devices

Memory	Mode	Resources Used		Performance					Unit
		LEs	M9K Memory	C6	C7, I7, A7	C8	C8L, I8L	C9L	
M9K Block	FIFO 256 × 36	47	1	315	274	238	200	157	MHz
	Single-port 256 × 36	0	1	315	274	238	200	157	MHz
	Simple dual-port 256 × 36 CLK	0	1	315	274	238	200	157	MHz
	True dual port 512 × 18 single CLK	0	1	315	274	238	200	157	MHz

Configuration and JTAG Specifications

Table 1–28 lists the configuration mode specifications for Cyclone IV devices.

Table 1–28. Passive Configuration Mode Specifications for Cyclone IV Devices (1)

Programming Mode	V_{CCINT} Voltage Level (V)	DCLK f_{MAX}	Unit
Passive Serial (PS)	1.0 (3)	66	MHz
	1.2	133	MHz
Fast Passive Parallel (FPP) (2)	1.0 (3)	66	MHz
	1.2 (4)	100	MHz

Notes to Table 1–28:

(1) For more information about PS and FPP configuration timing parameters, refer to the *Configuration and Remote System Upgrades in Cyclone IV Devices* chapter.

(2) FPP configuration mode supports all Cyclone IV E devices (except for E144 package devices) and EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 only.

(3) V_{CCINT} = 1.0 V is only supported for Cyclone IV E 1.0 V core voltage devices.

(4) Cyclone IV E devices support 1.2 V V_{CCINT}. Cyclone IV E 1.2 V core voltage devices support 133 MHz DCLK f_{MAX} for EP4CE6, EP4CE10, EP4CE15, EP4CE22, EP4CE30, and EP4CE40 only.

Table 1–29 lists the active configuration mode specifications for Cyclone IV devices.

Table 1–29. Active Configuration Mode Specifications for Cyclone IV Devices

Programming Mode	DCLK Range	Typical DCLK	Unit
Active Parallel (AP) *(1)*	20 to 40	33	MHz
Active Serial (AS)	20 to 40	33	MHz

Note to Table 1–29:

(1) AP configuration mode is only supported for Cyclone IV E devices.

Table 1–30 lists the JTAG timing parameters and values for Cyclone IV devices.

Table 1–30. JTAG Timing Parameters for Cyclone IV Devices *(1)*

Symbol	Parameter	Min	Max	Unit
t_{JCP}	TCK clock period	40	—	ns
t_{JCH}	TCK clock high time	19	—	ns
t_{JCL}	TCK clock low time	19	—	ns
t_{JPSU_TDI}	JTAG port setup time for TDI	1	—	ns
t_{JPSU_TMS}	JTAG port setup time for TMS	3	—	ns
t_{JPH}	JTAG port hold time	10	—	ns
t_{JPCO}	JTAG port clock to output *(2), (3)*	—	15	ns
t_{JPZX}	JTAG port high impedance to valid output *(2), (3)*	—	15	ns
t_{JPXZ}	JTAG port valid output to high impedance *(2), (3)*	—	15	ns
t_{JSSU}	Capture register setup time	5	—	ns
t_{JSH}	Capture register hold time	10	—	ns
t_{JSCO}	Update register clock to output	—	25	ns
t_{JSZX}	Update register high impedance to valid output	—	25	ns
t_{JSXZ}	Update register valid output to high impedance	—	25	ns

Notes to Table 1–30:

(1) For more information about JTAG waveforms, refer to "JTAG Waveform" in "Glossary" on page 1–37.

(2) The specification is shown for 3.3-, 3.0-, and 2.5-V LVTTL/LVCMOS operation of JTAG pins. For 1.8-V LVTTL/LVCMOS and 1.5-V LVCMOS, the output time specification is 16 ns.

(3) For EP4CGX22, EP4CGX30 (F324 and smaller package), EP4CGX110, and EP4CGX150 devices, the output time specification for 3.3-, 3.0-, and 2.5-V LVTTL/LVCMOS operation of JTAG pins is 16 ns. For 1.8-V LVTTL/LVCMOS and 1.5-V LVCMOS, the output time specification is 18 ns.

Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the high-speed I/O interface, external memory interface, and the PCI/PCI-X bus interface. I/Os using the SSTL-18 Class I termination standard can achieve up to the stated DDR2 SDRAM interfacing speeds. I/Os using general-purpose I/O standards such as 3.3-, 3.0-, 2.5-, 1.8-, or 1.5-LVTTL/LVCMOS are capable of a typical 200 MHz interfacing frequency with a 10 pF load.

Table 1–32. Emulated RSDS_E_1R Transmitter Timing Specifications for Cyclone IV Devices (1), (3) (Part 2 of 2)

Symbol	Modes	C6			C7, I7			C8, A7			C8L, I8L			C9L			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t_{LOCK} (2)	—	—	—	1	—	—	1	—	—	1	—	—	1	—	—	1	ms

Notes to Table 1–32:

(1) Emulated RSDS_E_1R transmitter is supported at the output pin of all I/O Banks of Cyclone IV E devices and I/O Banks 3, 4, 5, 6, 7, 8, and 9 of Cyclone IV GX devices.

(2) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Table 1–33. Mini-LVDS Transmitter Timing Specifications for Cyclone IV Devices (1), (2), (4)

Symbol	Modes	C6			C7, I7			C8, A7			C8L, I8L			C9L			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{HSCLK} (input clock frequency)	×10	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×8	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×7	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×4	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×2	5	—	200	5	—	155.5	5	—	155.5	5	—	155.5	5	—	132.5	MHz
	×1	5	—	400	5	—	311	5	—	311	5	—	311	5	—	265	MHz
Device operation in Mbps	×10	100	—	400	100	—	311	100	—	311	100	—	311	100	—	265	Mbps
	×8	80	—	400	80	—	311	80	—	311	80	—	311	80	—	265	Mbps
	×7	70	—	400	70	—	311	70	—	311	70	—	311	70	—	265	Mbps
	×4	40	—	400	40	—	311	40	—	311	40	—	311	40	—	265	Mbps
	×2	20	—	400	20	—	311	20	—	311	20	—	311	20	—	265	Mbps
	×1	10	—	400	10	—	311	10	—	311	10	—	311	10	—	265	Mbps
t_{DUTY}	—	45	—	55	45	—	55	45	—	55	45	—	55	45	—	55	%
TCCS	—	—	—	200	—	—	200	—	—	200	—	—	200	—	—	200	ps
Output jitter (peak to peak)	—	—	—	500	—	—	500	—	—	550	—	—	600	—	—	700	ps
t_{RISE}	20 – 80%, C_{LOAD} = 5 pF	—	500	—	—	500	—	—	500	—	—	500	—	—	500	—	ps
t_{FALL}	20 – 80%, C_{LOAD} = 5 pF	—	500	—	—	500	—	—	500	—	—	500	—	—	500	—	ps
t_{LOCK} (3)	—	—	—	1	—	—	1	—	—	1	—	—	1	—	—	1	ms

Notes to Table 1–33:

(1) Applicable for true and emulated mini-LVDS transmitter.

(2) Cyclone IV E—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated mini-LVDS transmitter is supported at the output pin of all I/O banks.
Cyclone IV GX—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.

(3) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Table 1–35. Emulated LVDS Transmitter Timing Specifications for Cyclone IV Devices (1), (3) (Part 2 of 2)

Symbol	Modes	C6		C7, I7		C8, A7		C8L, I8L		C9L		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{DUTY}	—	45	55	45	55	45	55	45	55	45	55	%
TCCS	—	—	200	—	200	—	200	—	200	—	200	ps
Output jitter (peak to peak)	—	—	500	—	500	—	550	—	600	—	700	ps
t_{LOCK} (2)	—	—	1	—	1	—	1	—	1	—	1	ms

Notes to Table 1–35:

(1) Cyclone IV E—emulated LVDS transmitter is supported at the output pin of all I/O Banks.
Cyclone IV GX—emulated LVDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.

(2) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Table 1–36. LVDS Receiver Timing Specifications for Cyclone IV Devices (1), (3)

Symbol	Modes	C6		C7, I7		C8, A7		C8L, I8L		C9L		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
f_{HSCLK} (input clock frequency)	×10	10	437.5	10	370	10	320	10	320	10	250	MHz
	×8	10	437.5	10	370	10	320	10	320	10	250	MHz
	×7	10	437.5	10	370	10	320	10	320	10	250	MHz
	×4	10	437.5	10	370	10	320	10	320	10	250	MHz
	×2	10	437.5	10	370	10	320	10	320	10	250	MHz
	×1	10	437.5	10	402.5	10	402.5	10	362	10	265	MHz
HSIODR	×10	100	875	100	740	100	640	100	640	100	500	Mbps
	×8	80	875	80	740	80	640	80	640	80	500	Mbps
	×7	70	875	70	740	70	640	70	640	70	500	Mbps
	×4	40	875	40	740	40	640	40	640	40	500	Mbps
	×2	20	875	20	740	20	640	20	640	20	500	Mbps
	×1	10	437.5	10	402.5	10	402.5	10	362	10	265	Mbps
SW	—	—	400	—	400	—	400	—	550	—	640	ps
Input jitter tolerance	—	—	500	—	500	—	550	—	600	—	700	ps
t_{LOCK} (2)	—	—	1	—	1	—	1	—	1	—	1	ms

Notes to Table 1–36:

(1) Cyclone IV E—LVDS receiver is supported at all I/O Banks.
Cyclone IV GX—LVDS receiver is supported at I/O Banks 3, 4, 5, 6, 7, 8, and 9.

(2) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

External Memory Interface Specifications

The external memory interfaces for Cyclone IV devices are auto-calibrating and easy to implement.

Table 1–46. Glossary (Part 2 of 5)

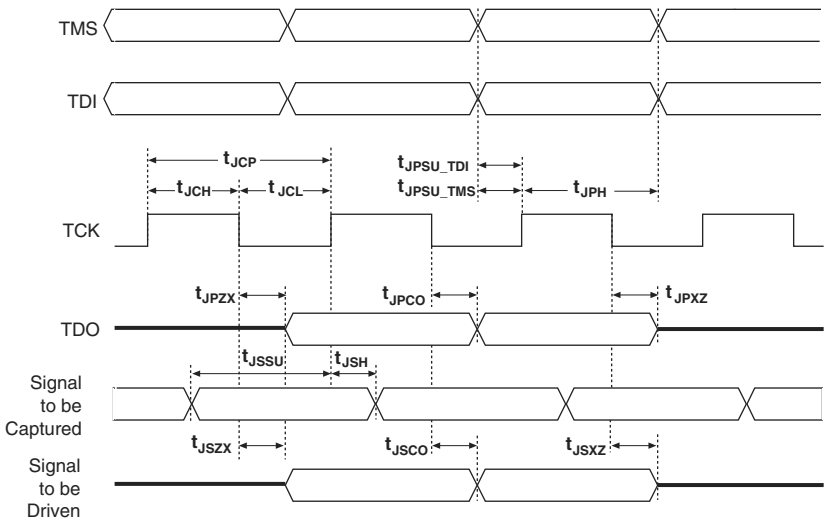
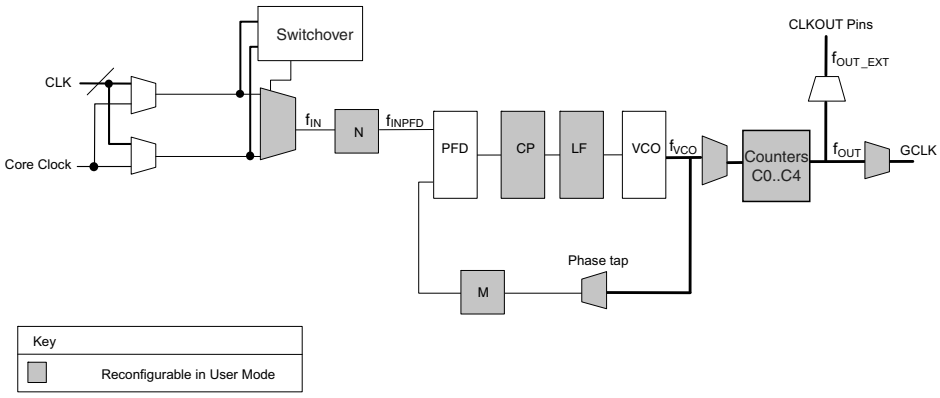
Letter	Term	Definitions
J	JTAG Waveform	
K	—	—
L	—	—
M	—	—
N	—	—
O	—	—
P	PLL Block	The following highlights the PLL specification parameters: 
Q	—	—

Table 1–46. Glossary (Part 4 of 5)

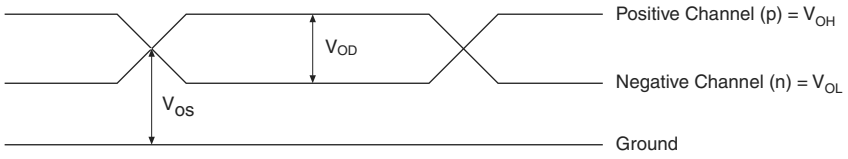
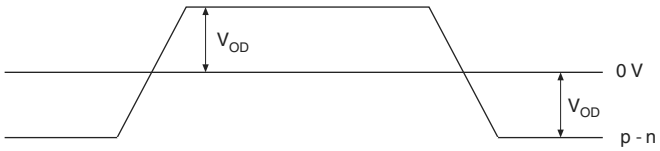
Letter	Term	Definitions
T	t_C	High-speed receiver and transmitter input and output clock period.
	Channel-to-channel-skew (TCCS)	High-speed I/O block: The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew. The clock is included in the TCCS measurement.
	t_{cin}	Delay from the clock pad to the I/O input register.
	t_{CO}	Delay from the clock pad to the I/O output.
	t_{cout}	Delay from the clock pad to the I/O output register.
	t_{DUTY}	High-speed I/O block: Duty cycle on high-speed transmitter output clock.
	t_{FALL}	Signal high-to-low transition time (80–20%).
	t_H	Input register hold time.
	Timing Unit Interval (TUI)	High-speed I/O block: The timing budget allowed for skew, propagation delays, and data sampling window. (TUI = 1/(Receiver Input Clock Frequency Multiplication Factor) = t_C/w).
	$t_{INJITTER}$	Period jitter on the PLL clock input.
	$t_{OUTJITTER\_DEDCLK}$	Period jitter on the dedicated clock output driven by a PLL.
	$t_{OUTJITTER\_IO}$	Period jitter on the general purpose I/O driven by a PLL.
	t_{plicin}	Delay from the PLL inclk pad to the I/O input register.
	$t_{plicout}$	Delay from the PLL inclk pad to the I/O output register.
	Transmitter Output Waveform	Transmitter output waveforms for the LVDS, mini-LVDS, PPDS and RSDS Differential I/O Standards: **Single-Ended Waveform**  **Differential Waveform (Mathematical Function of Positive & Negative Channel)** 
	t_{RISE}	Signal low-to-high transition time (20–80%).
	t_{SU}	Input register setup time.
U	—	—

Table 1–46. Glossary (Part 5 of 5)

Letter	Term	Definitions
V	$V_{CM(DC)}$	DC common mode input voltage.
	$V_{DIF(AC)}$	AC differential input voltage: The minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage: The minimum DC input differential voltage required for switching.
	V_{ICM}	Input common mode voltage: The common mode of the differential signal at the receiver.
	V_{ID}	Input differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	V_{IH}	Voltage input high: The minimum positive voltage applied to the input that is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage.
	$V_{IH(DC)}$	High-level DC input voltage.
	V_{IL}	Voltage input low: The maximum positive voltage applied to the input that is accepted by the device as a logic low.
	$V_{IL\ (AC)}$	Low-level AC input voltage.
	$V_{IL\ (DC)}$	Low-level DC input voltage.
	V_{IN}	DC input voltage.
	V_{OCM}	Output common mode voltage: The common mode of the differential signal at the transmitter.
	V_{OD}	Output differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter. $V_{OD} = V_{OH} – V_{OL}$.
	V_{OH}	Voltage output high: The maximum positive voltage from an output that the device considers is accepted as the minimum positive high level.
	V_{OL}	Voltage output low: The maximum positive voltage from an output that the device considers is accepted as the maximum positive low level.
	V_{OS}	Output offset voltage: $V_{OS} = (V_{OH} + V_{OL}) / 2$.
	$V_{OX\ (AC)}$	AC differential output cross point voltage: the voltage at which the differential output signals must cross.
	V_{REF}	Reference voltage for the SSTL and HSTL I/O standards.
	$V_{REF\ (AC)}$	AC input reference voltage for the SSTL and HSTL I/O standards. $V_{REF(AC)} = V_{REF(DC)}$ + noise. The peak-to-peak AC noise on V_{REF} must not exceed 2% of $V_{REF(DC)}$.
	$V_{REF\ (DC)}$	DC input reference voltage for the SSTL and HSTL I/O standards.
	$V_{SWING\ (AC)}$	AC differential input voltage: AC input differential voltage required for switching. For the SSTL differential I/O standard, refer to Input Waveforms.
	$V_{SWING\ (DC)}$	DC differential input voltage: DC input differential voltage required for switching. For the SSTL differential I/O standard, refer to Input Waveforms.
	V_{TT}	Termination voltage for the SSTL and HSTL I/O standards.
	$V_{X\ (AC)}$	AC differential input cross point voltage: The voltage at which the differential input signals must cross.
W	—	—
X	—	—
Y	—	—
Z	—	—